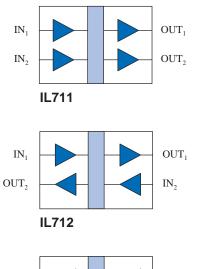
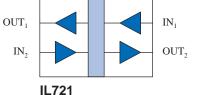


# High Speed/High Temperature Two-Channel Digital Isolators

#### **Functional Diagrams**





#### **Features**

- +5 V/+3.3 V CMOS / TTL Compatible
- High Speed: 150 Mbps Typical (S-Series)
- High Temperature: -40°C to +125°C (T-Series)
- 1.5 mA/Channel Typical Quiescent Current
- 300 ps Typical Pulse Width Distortion (S-Series)
- 100 ps Typical Pulse Jitter
- 2 ns Channel-to-Channel Skew
- 10 ns Typical Propagation Delay
- Low EMC Footprint
- 30 kV/µs Typical Common Mode Transient Immunity
- 2500 V<sub>RMS</sub> Isolation (1 min.)
- UL1577 and IEC 61010-2001 Approved
- 8-pin MSOP, SOIC, and PDIP Packages

#### **Applications**

- Board-to-Board Communication
- CANbus
- Peripheral Interfaces
- Logic Level Shifting

#### **Description**

NVE's IL700 family of high-speed digital isolators are CMOS devices manufactured with NVE's patented\* IsoLoop<sup>®</sup> spintronic Giant Magnetoresistive (GMR) technology. The IL711S and IL712S are the world's fastest two-channel isolators, with a 150 Mbps typical data rate for both channels.

The symmetric magnetic coupling barrier provides a typical propagation delay of only 10 ns and a pulse width distortion as low as 300 ps (0.3 ns), achieving the best specifications of any isolator. Typical transient immunity of 30 kV/ $\mu$ s is unsurpassed.

The IL711 has two transmit channels; the IL712 and IL721 have one transmit and one receive channel. The IL712 and IL721 operate full duplex, making them ideal for many fieldbus applications, including PROFIBUS, DeviceNet, and CAN. The IL721 has channels reversed to better suit certain board layouts.

The IL711 and IL712 are available in 8-pin MSOP, SOIC, and PDIP packages. The IL721 is available in an 8-pin SOIC package. Standard and S-Grade parts are specified over a temperature range of  $-40^{\circ}$ C to  $+100^{\circ}$ C; T-Grade parts have a maximum operating temperature of  $+125^{\circ}$ C.

IsoLoop is a registered trademark of NVE Corporation. \*U.S. Patent numbers 5,831,426; 6,300,617 and others.



# Absolute Maximum Ratings

Parameters	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Storage Temperature	Ts	-55		150	°C	
Ambient Operating Temperature <sup>(1)</sup> IL711T/ IL712T/IL721T	T <sub>A</sub>	-55		125 135	°C	
Supply Voltage	$V_{DD1}, V_{DD2}$	-0.5		7	V	
Input Voltage	VI	-0.5		$V_{DD} + 0.5$	V	
Output Voltage	Vo	-0.5		$V_{DD} + 0.5$	V	
Output Current Drive	Io			10	mA	
Lead Solder Temperature				260	°C	10 sec.
ESD			2		kV	HBM

#### **Recommended Operating Conditions**

Parameters	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Ambient Operating Temperature						
IL711/IL712 and IL711S/IL712S	T <sub>A</sub>	-40		100	°C	
IL711T/IL712T/IL721T		-40		125	°C	
Supply Voltage	$V_{DD1}, V_{DD2}$	3.0		5.5	V	
Logic High Input Voltage	V <sub>IH</sub>	2.4		V <sub>DD</sub>	V	
Logic Low Input Voltage	V <sub>IL</sub>	0		0.8	V	
Input Signal Rise and Fall Times	t <sub>IR</sub> , t <sub>IF</sub>			1	μs	

## **Insulation Specifications**

Parameters	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Creepage Distance						
MSOP		3.01			mm	
SOIC		4.03			mm	
PDIP		7.04			mm	
Leakage Current <sup>(5)</sup>			0.2		μΑ	240 V <sub>RMS</sub> , 60 Hz
Barrier Impedance <sup>(5)</sup>			>10 <sup>14</sup>   3		$\Omega \parallel pF$	

# **Package Characteristics**

Parameters	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Capacitance (Input–Output) <sup>(5)</sup>	C <sub>I-O</sub>		2		pF	f = 1 MHz
Thermal Resistance						
MSOP	$\theta_{JC}$		168		°C/W	Thermonounle et center
SOIC	$\theta_{\rm JC}$		144		°C/W	Thermocouple at center underside of package
PDIP	$\theta_{JC}$		54		°C/W	underside of package
Package Power Dissipation	$P_{PD}$			150	mW	$f = 1 \text{ MHz}, V_{DD} = 5 \text{ V}$

## Safety and Approvals

## IEC61010-1

TUV Certificate Numbers: N1502812, N1502812-101

#### **Classification as Reinforced Insulation**

		Pollution	Material	Max. Working
Model	Package	Degree	Group	Voltage
IL711-1; IL712-1	MSOP	II	III	150 V <sub>RMS</sub>
IL711-2; IL712-2	PDIP	II	III	300 V <sub>RMS</sub>
IL711-3; IL712-3; IL721-3	SOIC	II	III	150 V <sub>RMS</sub>

## UL 1577

Component Recognition Program File Number: E207481 Rated  $2500V_{RMS}$  for 1 minute

#### **Soldering Profile**

Per JEDEC J-STD-020C, MSL=2



# IL711/IL712/IL721

# **IL711 Pin Connections**

1	V <sub>DD1</sub>	Supply voltage
2	IN <sub>1</sub>	Data in, channel 1
3	IN <sub>2</sub>	Data in, channel 2
4	GND <sub>1</sub>	Ground return for V <sub>DD1</sub>
5	GND <sub>2</sub>	Ground return for V <sub>DD2</sub>
6	OUT <sub>2</sub>	Data out, channel 2
7	OUT <sub>1</sub>	Data out, channel 1
8	V <sub>DD2</sub>	Supply voltage

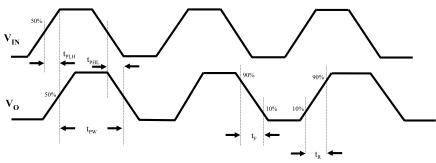
# **IL712 Pin Connections**

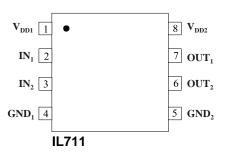
1	V <sub>DD1</sub>	Supply voltage
2	IN <sub>1</sub>	Data in, channel 1
3	OUT <sub>2</sub>	Data out, channel 2
4	GND <sub>1</sub>	Ground return for V <sub>DD1</sub>
5	GND <sub>2</sub>	Ground return for V <sub>DD2</sub>
6	IN <sub>2</sub>	Data in, channel 2
7	OUT <sub>1</sub>	Data out, channel 1
8	V <sub>DD2</sub>	Supply voltage

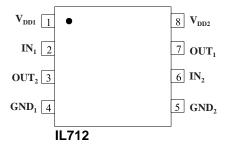
# **IL721 Pin Connections**

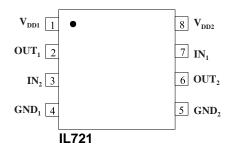
1	V <sub>DD1</sub>	Supply voltage
2	OUT <sub>1</sub>	Data out, channel 1
3	IN <sub>2</sub>	Data in, channel 2
4	GND <sub>1</sub>	Ground return for V <sub>DD1</sub>
5	GND <sub>2</sub>	Ground return for V <sub>DD2</sub>
6	OUT <sub>2</sub>	Data out, channel 2
7	IN <sub>1</sub>	Data in, channel 1
8	V <sub>DD2</sub>	Supply voltage

# Timing Diagram









t <sub>PLH</sub>	Propagation Delay, Low to High
t <sub>PHL</sub>	Propagation Delay, High to Low
t <sub>PW</sub>	Minimum Pulse Width
t <sub>R</sub>	Rise Time
t <sub>F</sub>	Fall Time



# **3.3 Volt Electrical Specifications**

Electrical specifications are  $T_{min}$  to  $T_{max}$  unless otherwise stated.

Parameters	Symbol	Min.	Тур.	Max.	Units	Test Conditions
		DC Specific	cations			·
Input Quiescent Supply Current						
IL711	т		8	10	μΑ	
IL712/IL721	I <sub>DD1</sub>		1.5	2	mA	
Output Quiescent Supply Current		•				•
IL711	т		3	4	mA	
IL712/IL721	I <sub>DD2</sub>		1.5	2	mA	
Logic Input Current	II	-10		10	μΑ	
Logic High Output Voltage	V <sub>OH</sub> V <sub>DD</sub> -	$V_{DD} - 0.1$	V <sub>DD</sub>		V	$I_0 = -20 \ \mu A, V_I = V_{IH}$
Logic High Output Voltage	V OH	0.8 x V <sub>DD</sub>	0.9 x V <sub>DD</sub>		v	$I_0 = -4 \text{ mA}, V_I = V_{IH}$
Logic Low Output Voltage	V <sub>OL</sub>		0	0.1	V	$I_0 = 20 \ \mu A, V_I = V_{IL}$
Logic Low Output Voltage	* OL		0.5	0.8	T Y	$I_0 = 4 \text{ mA}, V_I = V_{IL}$
	S	Switching Spee	cifications			
Maximum Data Rate						
IL711/IL712/IL721		100	110		Mbps	$C_L = 15 \text{ pF}$
IL711S/IL712S		130	140		Mbps	$C_L = 15 \text{ pF}$
IL711T/IL712T/IL721T		100	110		Mbps	$C_L = 15 \text{ pF}$
Pulse Width <sup>(7)</sup>	PW	10	7.5		ns	50% Points, Vo
Propagation Delay Input to Output	t <sub>PHL</sub>		12	18	ns	$C_L = 15 \text{ pF}$
(High to Low)	PHL		12	10	115	С_ = 15 рг
Propagation Delay Input to Output	t <sub>PLH</sub>		12	18	ns	$C_L = 15 \text{ pF}$
(Low to High)	PLH		12	10	115	$C_L = 15 \text{ pr}$
Pulse Width Distortion <sup>(2)</sup>						
IL711/IL712/IL721			2	3	ns	$C_L = 15 \text{ pF}$
IL711S/IL712S	PWD		2	3	ns	$C_L = 15 \text{ pF}$
IL711T/IL712T/IL721T			1	3	ns	$C_L = 15 \text{ pF}$
Propagation Delay Skew <sup>(3)</sup>	t <sub>PSK</sub>		4	6	ns	$C_L = 15 \text{ pF}$
Output Rise Time (10%–90%)	t <sub>R</sub>		2	4	ns	$C_L = 15 \text{ pF}$
Output Fall Time (10%–90%)	t <sub>F</sub>		2	4	ns	$C_L = 15 \text{ pF}$
Common Mode Transient Immunity	CM <sub>H</sub>  , CM <sub>L</sub>	20	30		kV/μs	$V_{CM} = 300 \text{ V}$
(Output Logic High or Logic Low) <sup>(4)</sup>		20	50		κν/μ3	
Channel-to-Channel Skew	t <sub>csk</sub>		2	3	ns	$C_L = 15 \text{ pF}$
Dynamic Power Consumption <sup>(6)</sup>			140	240	µA/MHz	per channel
	Magnetic Field I	(mmunity <sup>(8)</sup> (V		V <sub>DD1</sub> <5.5V)		
Power Frequency Magnetic Immunity	H <sub>PF</sub>	1000	1500		A/m	50Hz/60Hz
Pulse Magnetic Field Immunity	H <sub>PM</sub>	1800	2000		A/m	$t_p = 8\mu s$
Damped Oscillatory Magnetic Field	H <sub>OSC</sub>	1800	2000		A/m	0.1Hz – 1MHz
Cross-axis Immunity Multiplier <sup>(9)</sup>	K <sub>X</sub>		2.5			



# **5 Volt Electrical Specifications**

Electrical specifications are T<sub>min</sub> to T<sub>max</sub> unless otherwise stated.

Parameters	Symbol	Min.	Тур.	Max.	Units	Test Conditions
		DC Specifie	cations			
Input Quiescent Supply Current		-				
IL711	т		10	15	μΑ	
IL712/IL721	I <sub>DD1</sub>		2	3	mA	
Output Quiescent Supply Current		•				
IL711	Ŧ		4	6	mA	
IL712/IL721	I <sub>DD2</sub>		2	3	mA	
Logic Input Current	I	-10		10	μΑ	
Logic High Output Voltage	V <sub>OH</sub>	$V_{DD} - 0.1$	V <sub>DD</sub>		v	$I_0 = -20 \ \mu A, V_I = V_{IH}$
Logic High Output Voltage	V OH	0.8 x V <sub>DD</sub>	0.9 x V <sub>DD</sub>		v	$I_0 = -4 \text{ mA}, V_I = V_{IH}$
Logic Low Output Voltage	V <sub>OL</sub>		0	0.1	V	$I_0 = 20 \ \mu A, \ V_I = V_{IL}$
Logic Low Output Voltage	V OL		0.5	0.8	v	$I_0 = 4 \text{ mA}, V_1 = V_{11}$
		Switching Spe	cifications			
Maximum Data Rate						
IL711/IL712/IL721		100	110		Mbps	$C_L = 15 \text{ pF}$
IL711S/IL712S		130	150		Mbps	$C_L = 15 \text{ pF}$
IL711T/IL712T/IL721T		100	110		Mbps	$C_L = 15 \text{ pF}$
Pulse Width <sup>(7)</sup>	PW	10	7.5		ns	50% Points, Vo
Propagation Delay Input to Output	t		10	15	ns	$C_L = 15 \text{ pF}$
(High to Low)	t <sub>PHL</sub>		10	15	115	$C_{L} = 15 \text{ pr}^{2}$
Propagation Delay Input to Output	t <sub>PLH</sub>		10	15	ns	$C_{L} = 15 \text{ pF}$
(Low to High)	PLH		10	15	113	$C_{L} = 15 \text{ pr}$
Pulse Width Distortion <sup>(2)</sup>						
IL711/IL712/IL721			2	3	ns	$C_L = 15 \text{ pF}$
IL711S/IL712S	PWD		2	3	ns	$C_L = 15 \text{ pF}$
IL711T/IL712T/IL721T			0.3	3	ns	$C_L = 15 \text{ pF}$
Pulse Jitter <sup>(10)</sup>	t <sub>J</sub>		100		ps	$C_L = 15 \text{ pF}$
Propagation Delay Skew <sup>(3)</sup>	t <sub>PSK</sub>		4	6	ns	$C_L = 15 \text{ pF}$
Output Rise Time (10%–90%)	t <sub>R</sub>		1	3	ns	$C_L = 15 \text{ pF}$
Output Fall Time (10%–90%)	t <sub>F</sub>		1	3	ns	$C_L = 15 \text{ pF}$
Common Mode Transient Immunity	$ CM_{H} , CM_{L} $	20	30		kV/μs	$V_{cm} = 300 V$
(Output Logic High or Logic Low) <sup>(4)</sup>		20			R V/ µb	
Channel to Channel Skew	t <sub>CSK</sub>		2	3	ns	$C_L = 15 \text{ pF}$
Dynamic Power Consumption <sup>(6)</sup>			200	340	µA/MHz	per channel
	Magnetic Field			V <sub>DD1</sub> <5.5V)		
Power Frequency Magnetic Immunity	$H_{PF}$	2800	3500		A/m	50Hz/60Hz
Pulse Magnetic Field Immunity	H <sub>PM</sub>	4000	4500		A/m	$t_p = 8\mu s$
Damped Oscillatory Magnetic Field	H <sub>OSC</sub>	4000	4500		A/m	0.1Hz – 1MHz
Cross-axis Immunity Multiplier <sup>(9)</sup>	K <sub>X</sub>		2.5			

### Notes (apply to both 3.3 V and 5 V specifications):

- 1. Absolute maximum ambient operating temperature means the device will not be damaged if operated under these conditions. It does not guarantee performance.
- 2. PWD is defined as  $|t_{PHL} t_{PLH}|$ . %PWD is equal to PWD divided by pulse width.
- 3.  $t_{PSK}$  is the magnitude of the worst-case difference in  $t_{PHL}$  and/or  $t_{PLH}$  between devices at 25°C.
- 4.  $CM_{H}$  is the maximum common mode voltage slew rate that can be sustained while maintaining  $V_0 > 0.8 V_{DD2}$ .  $CM_L$  is the maximum common mode input voltage that can be sustained while maintaining  $V_0 < 0.8 V$ . The common mode voltage slew rates apply to both rising and falling common mode voltage edges.
- 5. Device is considered a two terminal device: pins 1–4 shorted and pins 5–8 shorted.
- 6. Dynamic power consumption is calculated per channel and is supplied by the channel's input side power supply.
- 7. Minimum pulse width is the minimum value at which specified PWD is guaranteed.
- 8. The relevant test and measurement methods are given in the Electromagnetic Compatibility section on p. 6.
- 9. External magnetic field immunity is improved by this factor if the field direction is "end-to-end" rather than to "pin-to-pin" (see diagram on p. 6).
- 10. 64k-bit pseudo-random binary signal (PRBS) NRZ bit pattern with no more than five consecutive 1s or 0s; 800 ps transition time.



# **Application Information**

## **Electrostatic Discharge Sensitivity**

This product has been tested for electrostatic sensitivity to the limits stated in the specifications. However, NVE recommends that all integrated circuits be handled with appropriate care to avoid damage. Damage caused by inappropriate handling or storage could range from performance degradation to complete failure.

# **Electromagnetic Compatibility**

IsoLoop Isolators have the lowest EMC footprint of any isolation technology. IsoLoop Isolators' Wheatstone bridge configuration and differential magnetic field signaling ensure excellent EMC performance against all relevant standards.

These isolators are fully compliant with generic EMC standards EN50081, EN50082-1 and the umbrella line-voltage standard for Information Technology Equipment (ITE) EN61000. NVE has completed compliance tests in the categories below:

EN50081-1

```
Residential, Commercial & Light Industrial
Methods EN55022, EN55014
```

EN50082-2: Industrial Environment

Methods EN61000-4-2 (ESD), EN61000-4-3 (Electromagnetic Field Immunity), EN61000-4-4 (Electrical Transient Immunity), EN61000-4-6 (RFI Immunity), EN61000-4-8 (Power Frequency Magnetic Field Immunity), EN61000-4-9 (Pulsed Magnetic Field), EN61000-4-10 (Damped Oscillatory Magnetic Field)

ENV50204

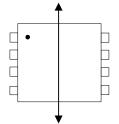
Radiated Field from Digital Telephones (Immunity Test)

Immunity to external magnetic fields is even higher if the field direction is "end-to-end" rather than to "pin-to-pin" as shown in the diagram below:

Cross-axis Field Direction

## **Dynamic Power Consumption**

IsoLoop Isolators achieve their low power consumption from the



way they transmit data across the isolation barrier. By detecting the edge transitions of the input logic signal and converting these to narrow current pulses, a magnetic field is created around the GMR Wheatstone bridge. Depending on the direction of the magnetic field, the bridge causes the output comparator to switch following the input logic signal. Since the current pulses are narrow, about 2.5 ns, the power consumption is independent of mark-to-space ratio and solely dependent on frequency. This has obvious advantages over optocouplers, which have power consumption heavily dependent on mark-to-space ratio.

# **Power Supply Decoupling**

Both power supplies to these devices should be decoupled with low-ESR 47 nF ceramic capacitors. Ground planes for both  $GND_1$ and  $GND_2$  are highly recommended for data rates above 10 Mbps. Capacitors must be located as close as possible to the V<sub>DD</sub> pins.

# Signal Status on Start-up and Shut Down

To minimize power dissipation, input signals are differentiated and then latched on the output side of the isolation barrier to reconstruct the signal. This could result in an ambiguous output state depending on power up, shutdown and power loss sequencing. Unless the circuit connected to the isolator performs its own poweron reset (POR), the designer should consider including an initialization signal in the start-up circuit. Initialization consists of toggling the input either high then low, or low then high. In CAN applications, the IL712 or IL721 should be used with CAN transceivers with Dominant Timeout functions for seamless POR. Most CAN transceiver manufacturers offer Dominant Timeout options. Examples include NXP's TJA 1050 and TJA 1040 transceivers.

## **Data Transmission Rates**

The reliability of a transmission system is directly related to the accuracy and quality of the transmitted digital information. For a digital system, those parameters which determine the limits of the data transmission are pulse width distortion and propagation delay skew.

Propagation delay is the time taken for the signal to travel through the device. This is usually different when sending a low-to-high than when sending a high-to-low signal. This difference, or error, is called pulse width distortion (PWD) and is usually in nanoseconds. It may also be expressed as a percentage:

$$PWD\% = \frac{Maximum Pulse Width Distortion (ns)}{Signal Pulse Width (ns)} \times 100\%$$

For example, with data rates of 12.5 Mbps:

$$PWD\% = \frac{3 \text{ ns}}{80 \text{ ns}} \times 100\% = 3.75\%$$

This figure is almost **three times** better than any available optocoupler with the same temperature range, and **two times** better than any optocoupler regardless of published temperature range. IsoLoop isolators exceed the 10% maximum PWD recommended by PROFIBUS, and will run to nearly 35 Mb within the 10% limit.

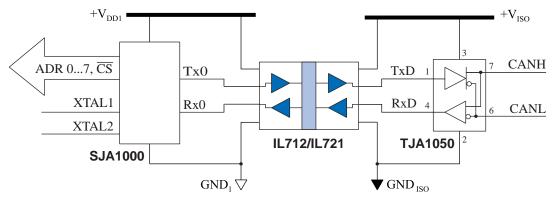
Propagation delay skew is the signal propagation difference between two or more channels. This becomes significant in clocked systems because it is undesirable for the clock pulse to arrive before the data has settled. Short propagation delay skew is therefore especially critical in high data rate parallel systems for establishing and maintaining accuracy and repeatability. Worstcase channel-to-channel skew in an IL700 Isolator is only 3 ns, which is **ten times** better than any optocoupler. IL700 Isolators have a maximum propagation delay skew of 6 ns, which is **five times** better than any optocoupler.



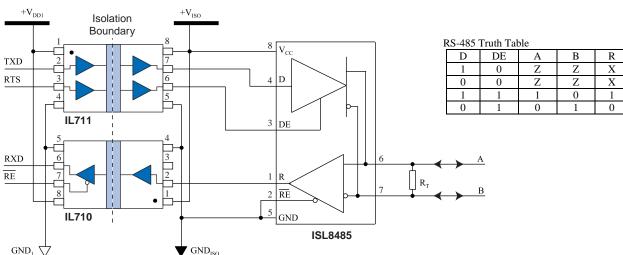
# IL711/IL712/IL721

# **Illustrative Applications**

## **Isolated CAN**



In today's CAN networks, node-to-node isolation is increasingly recommended by designers to reduce EMI susceptibility, especially in highspeed applications and in hybrid and electrical vehicle networks, where the 12 V battery has been replaced with one of several hundred volts. Operator and equipment safety becomes critical when a high voltage source, such as the battery, needs to be connected to diagnosis systems during routine maintenance procedures. In the application shown above, the microcontroller is isolated from the CAN transceiver by an IL712 or IL721, allowing higher speed and more reliable bus operation by eliminating ground loops and reducing susceptibility to noise and EMI events. The best-in-class 10 ns typical IL712/IL721 propagation delay minimizes CAN loop delay and maximizes data rate over any given bus length. The simple circuit works with any CAN transceiver with a TxD dominant timeout, which includes all of the current-generation transceivers.



#### Isolated PROFIBUS / RS-485

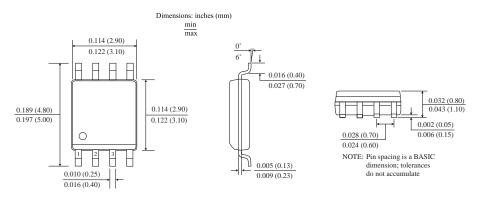
NVE offers a unique line of PROFIBUS / RS-485 transceivers, but IL700 high-speed digital signal isolators can also be used as part of multi-chip designs with non-isolated PROFIBUS transceivers.



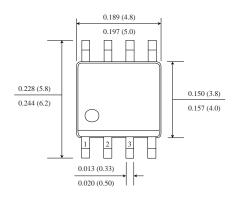


## Package Drawings, Dimensions and Specifications

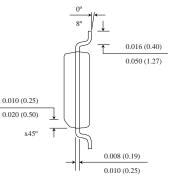
#### 8-pin MSOP

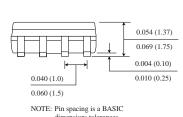


# 8-pin SOIC Package



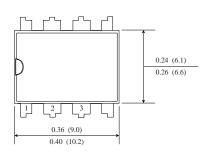
Dimensions in inches (mm)

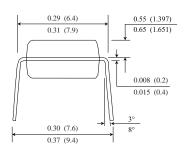


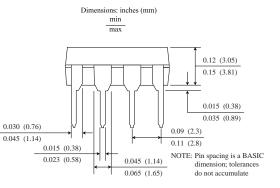


dimension; tolerances do not accumulate

# 8-pin PDIP

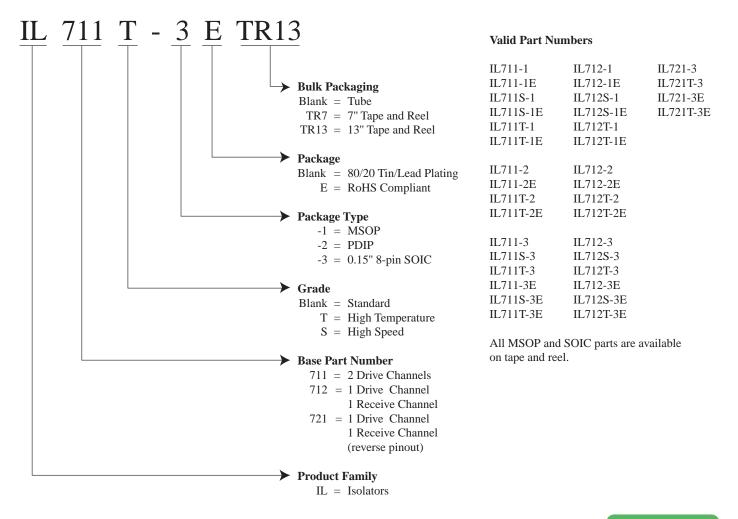








## Ordering Information and Valid Part Numbers







ISB-DS-001-IL711/12-Z March 2012	<ul><li>Changes</li><li>Tightened IL711 typ. output quiescent supply spec. from 3.3 mA to 3 mA at 3.3V.</li></ul>
ISB-DS-001-IL711/12-Y	<ul><li>Changes</li><li>Updates to terms and conditions.</li></ul>
ISB-DS-001-IL711/12-X	<ul><li>Changes</li><li>Changed MSOP pin spacing (p. 8).</li></ul>
ISB-DS-001-IL711/12-W	<ul><li>Changes</li><li>Changed MSOP pin spacing (p. 8).</li></ul>
	• Clarified S-Series and T-Series speed specifications.
ISB-DS-001-IL711/12-V	<ul><li>Changes</li><li>Added IL721 configuration.</li></ul>
ISB-DS-001-IL711/12-U	<ul><li>Changes</li><li>Added CAN application diagram (p. 7).</li></ul>
ISB-DS-001-IL711/12-T	<ul><li>Changes</li><li>Added typical jitter specification at 5V.</li></ul>
ISB-DS-001-IL711/12-S	<ul><li>Changes</li><li>Added EMC details.</li></ul>
ISB-DS-001-IL711/12-R	<ul><li>Changes</li><li>IEC 61010 approval for MSOP versions.</li></ul>
ISB-DS-001-IL711/12-Q	<ul> <li>Changes</li> <li>Added magnetic field immunity and electromagnetic compatibility specifications.</li> </ul>
ISB-DS-001-IL711/12-P	<ul><li>Changes</li><li>Correct SOIC package drawing.</li></ul>
ISB-DS-001-IL711/12-0	<ul> <li>Changes</li> <li>Note on all package drawings that pin-spacing tolerances are non-accumulating; change MSOP pin-spacing dimensions and tolerance accordingly.</li> </ul>
ISB-DS-001-IL711/12-N	<ul><li>Changes</li><li>Changed lower limit of length on PDIP package drawing.</li></ul>
	• Tightened pin-spacing tolerance on MSOP package drawing.
ISB-DS-001-IL711/12-M	<ul> <li>Changes</li> <li>Changed ordering information to reflect that devices are now fully RoHS compliant with no exemptions.</li> </ul>
ISB-DS-001-IL711/12-L	<ul><li>Changes</li><li>Eliminated soldering profile chart</li></ul>
ISB-DS-001-IL711/12-K	<ul><li>Changes</li><li>Added RS-485 application circuit</li></ul>





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